- 12 A Continuous On-State Current
- 100 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA

TO-220 PACKAGE

Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	TIC126D		400		
Repetitive peak off-state voltage	TIC126M	V	600	V	
	TIC126S	V _{DRM}	700		
	TIC126N		800		
Repetitive peak reverse voltage	TIC126D		400		
	TIC126M	\/	600	V	
	TIC126S	V _{RRM}	700		
	TIC126N		800		
Continuous on-state current at (or below) 70°C case temperature (see Note 1)		I _{T(RMS)}	12	Α	
Average on-state current (180° conduction angle) at (or below) 70°C case temperature		L	7.5	Α	
(see Note 2)		I _{T(AV)}	7.5	^	
Surge on-state current at (or below) 25°C case temperature (see Note 3)		I _{TM}	100	Α	
Peak positive gate current (pulse width ≤ 300 μs)		I _{GM}	3	Α	
Peak gate power dissipation (pulse width ≤ 300 μs)		P _{GM}	5	W	
Average gate power dissipation (see Note 4)		P _{G(AV)}	1	W	
Operating case temperature range		T _C	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds		T _L	230	°C	

- NOTES: 1. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 2. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 4. This value applies for a maximum averaging time of 20 ms.



TIC126 SERIES SILICON CONTROLLED RECTIFIERS

APRIL 1971 - REVISED JUNE 2000

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNIT			
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}		T _C = 110°C			2	mA
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			2	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		8	20	mA
V _{GT} Gate		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = - 40°C			2.5	
	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$			0.8	1.5	V
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = 110°C	0.2			
I _H Holding current	Holding current	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$		T _C = - 40°C			100	mA
	riolanig darrent	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$					40	
V _T	On-state voltage	I _T = 12 A	(see Note 5)				1.4	V
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	I _G = 0	T _C = 110°C		400		V/µs

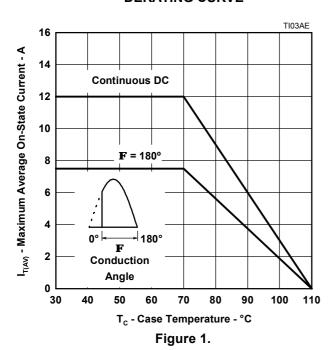
NOTE 5: This parameter must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			2.4	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

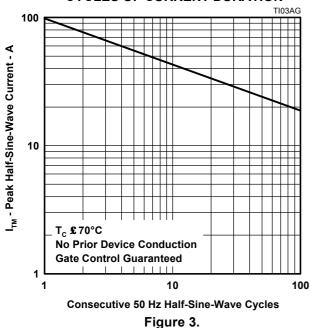
THERMAL INFORMATION

AVERAGE ON-STATE CURRENT DERATING CURVE

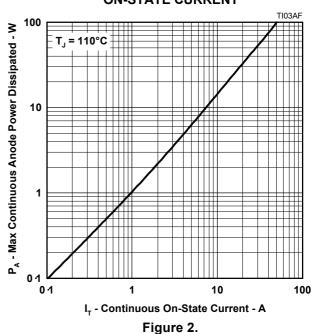


SURGE ON-STATE CURRENT vs

CYCLES OF CURRENT DURATION

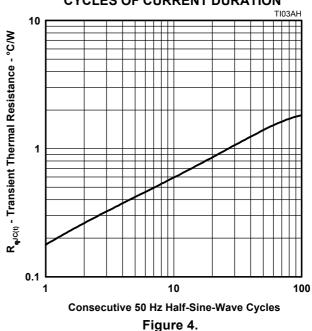


MAX ANODE POWER LOSS vs ON-STATE CURRENT



TRANSIENT THERMAL RESISTANCE

CYCLES OF CURRENT DURATION

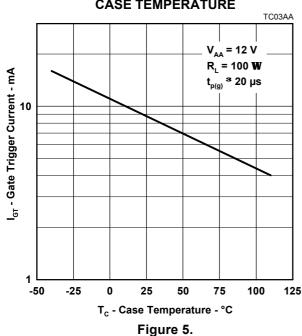


Power

TYPICAL CHARACTERISTICS

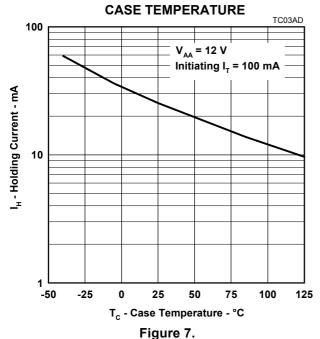
GATE TRIGGER CURRENT vs

CASE TEMPERATURE



HOLDING CURRENT

VS



GATE TRIGGER VOLTAGE

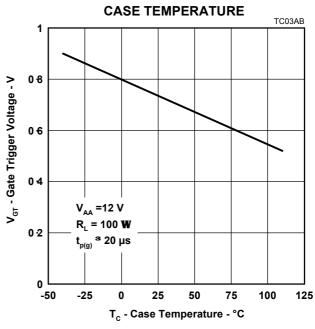
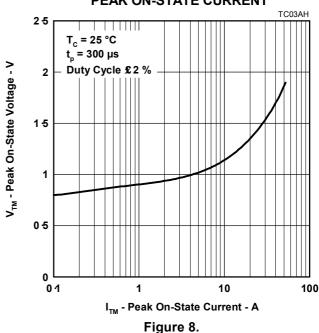


Figure 6.

PEAK ON-STATE VOLTAGE VS

PEAK ON-STATE CURRENT



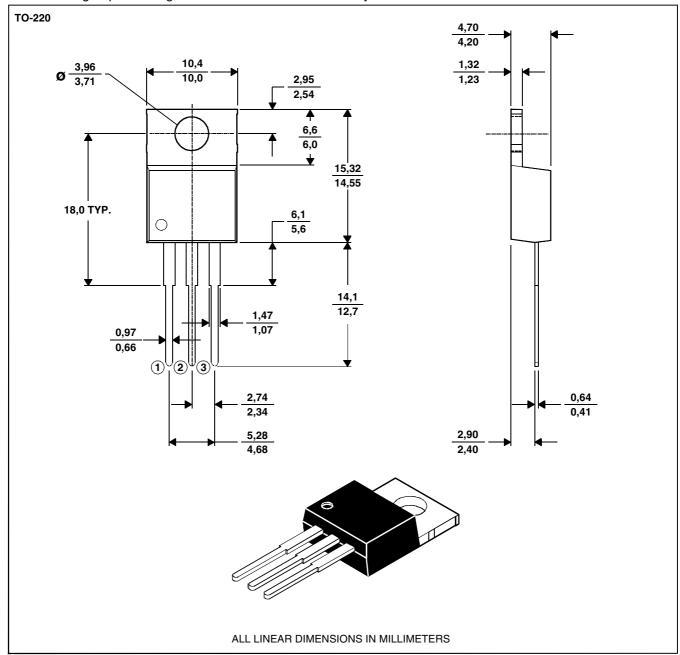
PRODUCT INFORMATION

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.



TIC126 SERIES SILICON CONTROLLED RECTIFIERS

APRIL 1971 - REVISED JUNE 2000

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